An Overview of the Target Fabrication Activities at Technical University Darmstadt



Thomas Heßling (GSI,TUD) Dr. Gabriel Schaumann (RAL) Prof. Dr. Markus Roth (TUD)

Talk by Dennis Schumacher (TUD)

An Overview of the Target Fabrication Activities at Technical University Darmstadt



- Reasons for the target facility at the TUD
- Possible target geometries
- Production steps
- Outlook



Reasons for the target facility at the TUD

Energy loss of heavy ions in dense plasma: foil target Direct laser heated target laser ion beam plasma converter hohlraum Indirect heated target laser § x-ray ion beam foil target target hohlraum



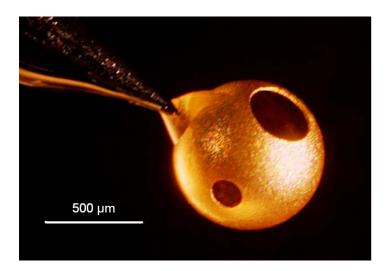


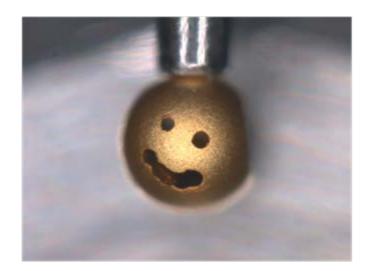
Possible target geometries



Spherical hohlraumtargets

- Diameter: 400μm 1000μm
- Wall thickness: 10µm
- Different hole forms and sizes starting from 5µm diameter





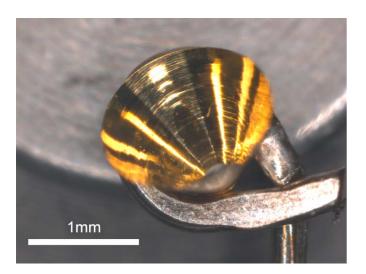


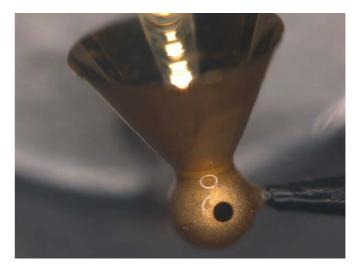
Possible target geometries



Cones

Diameter (big end) 1.5 mmWall thickness 10 µm







Compound targets

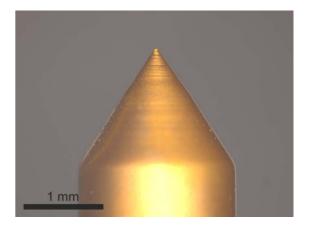
Blank





Mandrel for cones Brass mandrel

Fabricated with a lathe





Electroplating and photo lithography

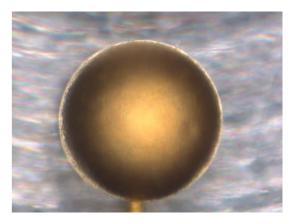
Electroplating with gold layer
KCN Au complex
Plating current density: 2mA/cm²
Plating time: 80 min

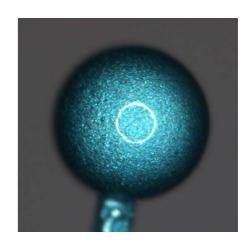
Photo lithography
Photo resist is deposited by electroplating
3d surfaces can be coated
Resist thickness depends on:

voltage
two additives in the resist solution
temperature

Thickness range: 2µm to 40µm
Positive resist





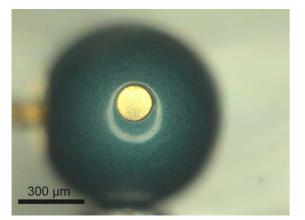




Exposure

- Exposure under microscope
- Sensitive to wavelengths shorter than 420nm
- UV light by mercury lamp
- Conducted by glass fibre
- Aperture for different sizes and forms
- Demagnified by microscope optics

 Removal of the exposed resist by a weak caustic soda solution









Exposure

Gold etching •Etched by potassium iodide-iodine solution

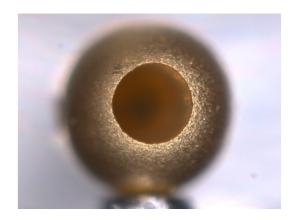
Removal of the photo resist •Removed by a strong caustic soda solution

Brass etchingEtched through the holes with nitric acid

Stainless steel etching •Etched with hydrochloric acid









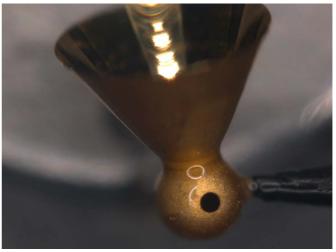
Assembling

Assemble different Targets together •Alignment by micro assembly station and microscope •Glued together with a UV curing glue

Double hohlraumtarget:



Cone with hohlraumtarget:





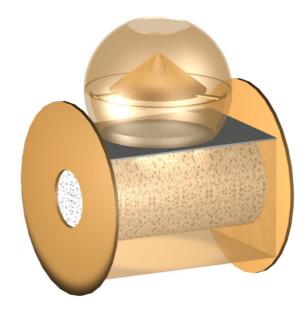


Outlook



Laser drilled holes with titan:sapphire Laser

- Barrel plating
- Stainless steel blank
 Better surface
 More diameters available
 Chrome oxide layer
 - More difficult to etch
- Foil and foam filled hohlraumtargets
- Cone in a spherical target







Thank you for your attention

